Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .004” X .004”**

**Backside Potential: COLLECTOR**

**Process: 76**

**APPROVED BY: DK DIE SIZE .027” X .033” DATE: 11/16/21**

**MFG: FAIRCHILD THICKNESS .008” P/N: MMBTA92**

**DG 10.1.2**

#### Rev B, 7/19/02